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Guidelines for Design, Selection and Application of Potting Materials and Encapsulation Processes Used for Electronics Printed Circuit Board Assembly

A standard developed by IPC

Association Connecting Electronics Industries

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In May 1995 the IPC's Technical Activities Executive Committee (TAEC) adopted Principles of Standardization as a guiding principle of IPC's standardization efforts.

Standards Should:

- Show relationship to Design for Manufacturability (DFM) and Design for the Environment (DFE)
- Minimize time to market
- Contain simple (simplified) language
- Just include spec information
- Focus on end product performance
- Include a feedback system on use and problems for future improvement

Standards Should Not:

- Inhibit innovation
- Increase time-to-market
- Keep people out
- Increase cycle time
- Tell you how to make something
- Contain anything that cannot be defended with data

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Guidelines for Design, Selection and Application of Potting Materials and Encapsulation Processes Used for Electronics Printed Circuit Board Assembly

Developed by the Potting and Encapsulation Task Group (5-33f) of the Cleaning and Coating Committee (5-30) of IPC

Users of this publication are encouraged to participate in the development of future revisions.

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